

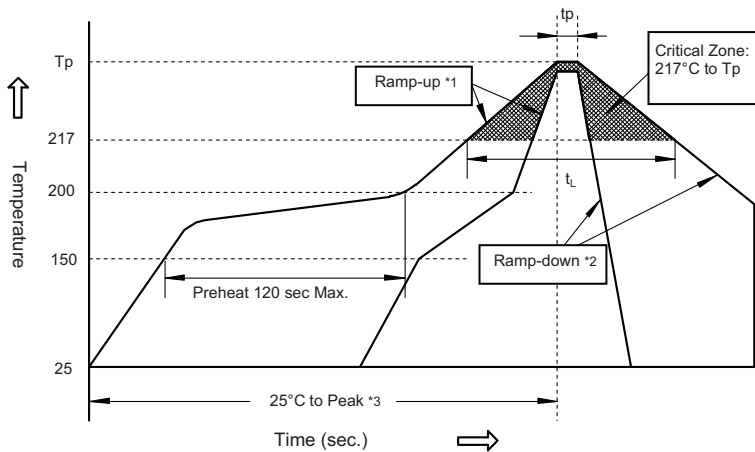
Reflow Soldering Condition for Chip Electrolytic Capacitors (SMD)

Applicable to Chip Type Aluminum Electrolytic Capacitors

Recommended Conditions for Reflow Soldering

- (1) A thermal condition system such as infrared radiation (IR) or hot blast should be adopted, and vapor heat transfer systems (VPS) are not recommended.
- (2) Reflow soldering should be within 2 cycles. Please make sure that the parts have enough cooling time.
- (3)
 - The time of preheating from 150°C to 200°C shall be within maximum 120 seconds;
 - The time of soldering temperature at 217°C measured on capacitors' top shall not exceed t_L (second);
 - The peak temperature on capacitors' top shall not exceed T_p (°C), and the time within 5°C of actual peak temperature shall not exceed t_p (second).

Classification Reflow Profile



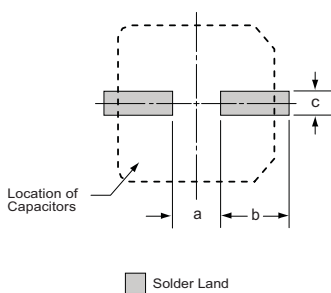
- *1. Average ramp-up rate is 3°C/second max.
- *2. Ramp-down rate is 6°C /second max.
- *3. Time from 25°C to peak temperature is 6 minutes max.

Classified at Temperature and Time

| Size | Thickness (mm) | T_p (°C) | t_L (second) | t_p (second) |
|------------------|----------------|------------|----------------|----------------|
| Ø4~Ø6.3, Ø8×6.2L | ≥2.5 | 255 | 60 | 5 |
| Ø8×10.5L | ≥2.5 | 250 | 60 | 5 |
| Ø10×10.5L/13.5L | ≥2.5 | 245 | 60 | 5 |
| Ø12.5, Ø16 | ≥2.5 | 240 | 40 | 5 |

● Please contact us if your condition is over the maximum.

Recommended Solder Land Size on PC Board (Unit: mm)



| Size | a | b | c |
|----------|-----|-----|-----|
| Ø4 | 1.0 | 2.6 | 1.6 |
| Ø5 | 1.4 | 3.0 | 1.6 |
| Ø6.3 | 1.9 | 3.5 | 1.6 |
| Ø8×6.2L | 2.1 | 4.0 | 1.6 |
| Ø8×10.5L | 3.0 | 3.5 | 2.5 |
| Ø10 | 4.0 | 4.0 | 2.5 |
| Ø12.5 | 4.0 | 6.0 | 3.2 |
| Ø16 | 6.0 | 7.0 | 3.5 |